

Electronic Patent Application Fee Transmittal

Application Number:	10540992
Filing Date:	05-Jun-2006
Title of Invention:	Chemical-mechanical-polishing slurry composition, method for planarizing surface of semiconductor device using the same, and method for controlling selection ratio of slurry composition
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Attorney Docket Number:	061063-0316598

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810